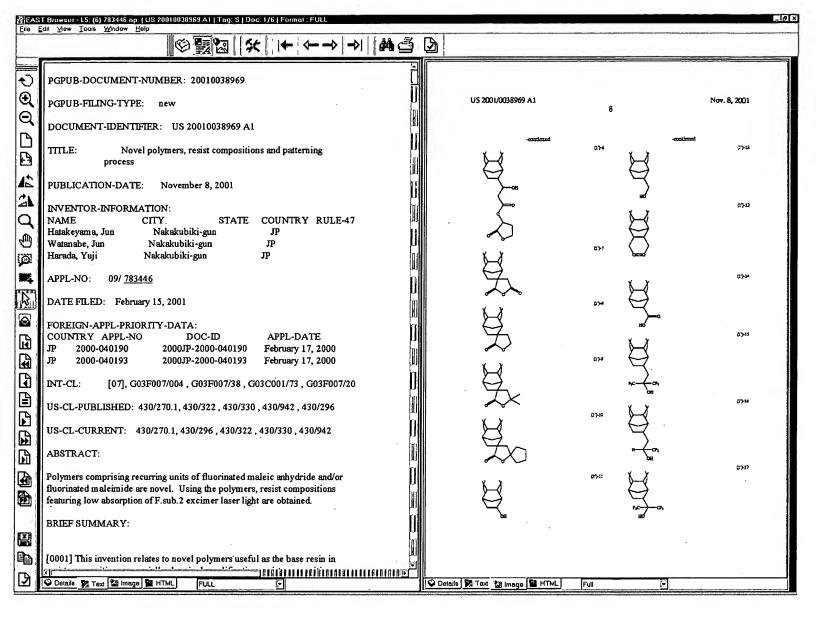
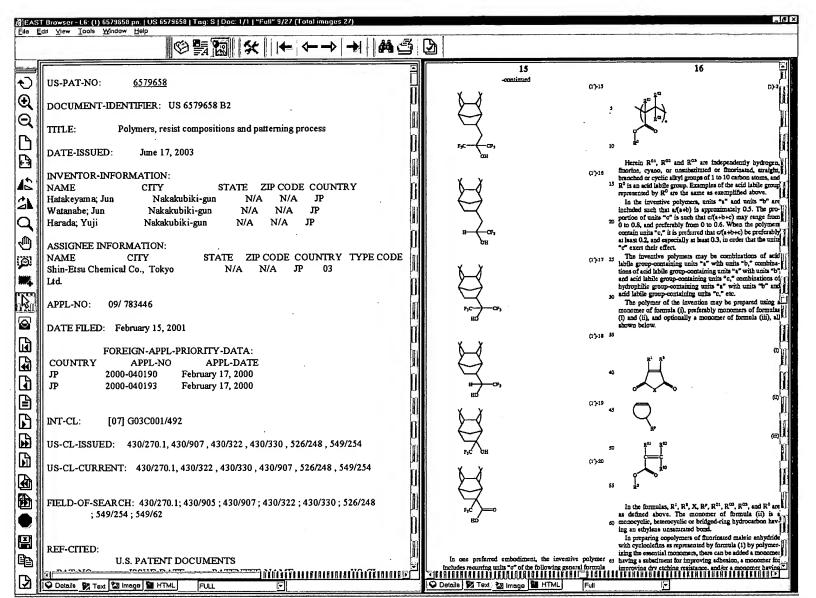
(FILE 'HOME' ENTERED AT 17:12:54 ON 04 AUG 2003) FILE 'REGISTRY' ENTERED AT 17:13:01 ON 04 AUG 2003 STRUCTURE UPLOADED		
L1		(FILE 'HOME' ENTERED AT 17:12:54 ON 04 AUG 2003)
L3		STRUCTURE UPLOADED
L7	L4 L5	269 S L2 1507622 S POLYMER OR COPOLYMER OR RESIN 5 S L3 AND L4
L10	L7 L8	SCREEN 2067 4 S L1
FILE 'CAPLUS' ENTERED AT 17:20:15 ON 04 AUG 2003 L12	L10	2 S L9
### Tile 'REGISTRY' ENTERED AT 17:20:33 ON 04 AUG 2003 ### STRUCTURE UPLOADED ### STRUCTURE UPLOADED ### STRUCTURE UPLOADED ### STRUCTURE AT 17:21:21 ON 04 AUG 2003 ### L15		FILE 'REGISTRY' ENTERED AT 17:19:59 ON 04 AUG 2003
L13	L12	
L15	L13	STRUCTURE UPLOADED
L17 STRUCTURE UPLOADED L18 126 S L17 FULL FILE 'CAPLUS' ENTERED AT 17:31:11 ON 04 AUG 2003 L19 17 S L4 AND L18 L20 8 S L6 AND L19 FILE 'REGISTRY' ENTERED AT 17:38:49 ON 04 AUG 2003 L21 STRUCTURE UPLOADED L22 651 S L21 FULL L23 STRUCTURE UPLOADED L24 STRUCTURE UPLOADED L25 1 S L23 FULL L26 126 S L24 FULL FILE 'CAPLUS' ENTERED AT 17:40:23 ON 04 AUG 2003	L15	152 S L4 AND L14
L19	L17	STRUCTURE UPLOADED
L21 STRUCTURE UPLOADED L22 651 S L21 FULL L23 STRUCTURE UPLOADED L24 STRUCTURE UPLOADED L25 1 S L23 FULL L26 126 S L24 FULL . FILE 'CAPLUS' ENTERED AT 17:40:23 ON 04 AUG 2003		
	L22 L23 L24 L25	STRUCTURE UPLOADED 651 S L21 FULL STRUCTURE UPLOADED STRUCTURE UPLOADED 1 S L23 FULL
	L27	

=>





```
ANSWER 1 OF 5 CAPLUS COPYRIGHT 2003 ACS on STN
L5
    2003:301117 CAPLUS
AN
DN
    138:304711
    Novel fluoropolymer, resist compositions containing the same, and novel
ΤI
    fluoromonomers
    Araki, Takayuki; Ishikawa, Takuji; Koh, Meiten
IN
PA
    Daikin Industries, Ltd., Japan
SO
    PCT Int. Appl., 153 pp.
    CODEN: PIXXD2
DT
     Patent
     Japanese
LA
FAN.CNT 1
                     KIND DATE
                                          APPLICATION NO. DATE
    PATENT NO.
                                          _____
                     ____
     _____
                          20030417
                                         WO 2002-JP10242 20021002
PΤ
    WO 2003031487
                     A1
        W: JP, KR, US
        RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT,
            LU, MC, NL, PT, SE, SK, TR
PRAI JP 2001-307823
                           20011003
                    Α
    JP 2002-54964
                      Α
                           20020228
OS
    MARPAT 138:304711
    The present invention relates to a fluorocopolymer having aliph.
AB
    monocyclic structures in the backbone chain, as represented by the general
    formula (M1) (M2a) (N) wherein structural unit (M1) is a unit derived from
     an ethylenic monomer having two or three carbon atoms and at least one
    fluorine atom; structural unit (M2a) is at least one kind of unit
    represented by the general formula I and forming an aliph. monocyclic
     structure in the backbone chain; and structural unit (N) is a unit derived
    from a monomer copolymerizable with structural units (M1) and (M2a), which
    comprises 1 to 99 mol% of structural units (M1), 1 to 99 mol% of
    structural units (M2a) and 0 to 98 mol% of structural units (N) and has a
    no.-av. mol. wt. of 500 to 1,000,000. In the formula I, R1 is at least
    one group selected from among divalent hydrocarbon groups which each have
    one to eight ring-constituting carbon atoms and may be substituted with
    hydrocarbyl or fluoroalkyl, and divalent hydrocarbon groups which each
    have an ether linkage with the sum of ring-constituting carbon and oxygen
    atoms ranging from 2 to 8 and may be substituted with hydrocarbyl or
     fluoroalkyl; R2 is alkylene having one to three ring-constituting carbon
     atoms; R3 and R4 are each independently alkylene having one or two carbon
     atoms; and n1, n2, and n3 are each independently 0 or 1. This
     fluorocopolymer exhibits excellent dry etching resistance and transparency
     in the vacuum UV region. Thus, 3.4 g cyclopentene and 10.0 g
     tetrafluoroethylene were reacted in HCFC 141b contg. bis(4-tert-
    butylcyclohexyl) peroxydicarbonate to give a 50:50 mol% copolymer
    with Mn 5700.
TT
     509085-42-1P
    RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT
```

(Reactant or reagent)

(intermediate in monomer prepn.; prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)

RN 509085-42-1 CAPLUS

Cyclopentene, 3,5-bis(ethoxymethoxy)-4,4-difluoro-3,5-bis(trifluoromethyl)-CN (9CI) (CA INDEX NAME)

IT 509085-43-2P

RL: IMF (Industrial manufacture); PREP (Preparation) (monomer; prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)
RN 509085-43-2 CAPLUS
CN 4-Cyclopentene-1,3-diol, 2,2-difluoro-1,3-bis(trifluoromethyl)- (9CI) (CA INDEX NAME)

IT 509085-39-6P

RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent) (monomer; prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)

RN 509085-39-6 CAPLUS

CN 2-Cyclopentene-1-methanol, .alpha.,.alpha.-bis(trifluoromethyl)- (9CI)- (CA INDEX NAME)

IT 509085-40-9P

RL: IMF (Industrial manufacture); PRP (Properties); RCT (Reactant); TEM (Technical or engineered material use); PREP (Preparation); RACT (Reactant or reagent); USES (Uses)

(prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)

RN 509085-40-9 CAPLUS

CN 2-Cyclopentene-1-methanol, .alpha.,.alpha.-bis(trifluoromethyl)-, polymer
with tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 509085-39-6 CMF C8 H8 F6 O

CM 2

CRN 116-14-3 CMF C2 F4

IT 509085-40-9DP, hydrolyzed

RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)

RN 509085-40-9 CAPLUS

CN 2-Cyclopentene-1-methanol, .alpha.,.alpha.-bis(trifluoromethyl)-, polymer with tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 509085-39-6 CMF C8 H8 F6 O

CM 2

CRN 116-14-3 CMF C2 F4

RE.CNT 2 THERE ARE 2 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L5 ANSWER 2 OF 5 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2002:353506 CAPLUS

DN 136:377479

TI High-molecular compounds for photoresists, monomeric compounds, photosensitive resin compositions, method for forming patterns with the compositions, and process for production of electronic components

IN Shida, Naomi; Ushirogouchi, Toru; Naito, Takuya

PA Kabushiki Kaisha Toshiba, Japan

SO PCT Int. Appl., 321 pp. CODEN: PIXXD2

DT Patent

LA Japanese

FAN.CNT 1

FAN. CNT 1									
PATENT	NO.	KIND	DATE	APPLICATION NO.	DATE				
	-								
PI WO 200:	2036646	A1	20020510	WO 2001-JP9567	20011031				
W:	KR, US								
JP 200	2201219	A2	20020719	JP 2001-295012	20010926				
PRAI JP 2000	0-332358	Α	20001031						
JP 200	1-295012	Α	20010926						
OS MARPAT	136:377479			·					

AB High-mol. compds. for photoresists, each having at least one skeleton represented by the general formula -RC(Rx1)2(ORx1), I, II, or III:
-RC(Rx1)2(ORx1) I II III(R = alicyclic skeleton; Rx1= electron-attracting group, H, monovalent org. group). The compds. shows small absorption towards .ltoreq.160 nm light and provides the fine resist pattern of nanometer size and of the high etching resistance.

IT 424825-88-7P 424825-93-4P 424825-96-7P 424825-99-0P 424826-05-1P 424826-07-3P

RL: SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(high-mol. compds. for photoresists)

RN 424825-88-7 CAPLUS

CN 2,5-Furandione, polymer with 3-ethenyltetrahydro-5-(2-tricyclo[3.3.1.13,7]dec-1-ylethyl)-2,2-bis(trifluoromethyl)furan and 1,3,3-tris(trifluoromethyl)-2-oxabicyclo[3.2.1]oct-6-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-87-6 CMF C20 H26 F6 O

$$F_3C$$
 CH_2-CH_2
 H_2C
 CH

CM 2

CRN 424825-86-5 CMF C10 H7 F9 O

CM 3

CRN 108-31-6 CMF C4 H2 O3

RN 424825-93-4 CAPLUS

CN 2H-Pyran, tetrahydro-2-[[7-(trifluoromethyl)bicyclo[2.2.1]hept-2-en-7-yl]oxy]-, polymer with 2,2,5,5-tetrafluoro-2,5-dihydrofuran (9CI) (CA INDEX NAME)

CM 1

CRN 424825-92-3 CMF C13 H17 F3 O2

CRN 24565-48-8 CMF C4 H2 F4 O

RN 424825-96-7 CAPLUS

CN Furan, 2,5-dihydro-2,2,5,5-tetrakis(pentafluoroethyl)-, polymer with 1-[2,2,2-trifluoro-1-[(2-methoxyethoxy)methoxy]-1- (trifluoromethyl)ethyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-95-6 CMF C12 H2 F20 O

CM 2

CRN 424825-94-5 CMF C14 H18 F6 O3

RN 424825-99-0 CAPLUS

CN Furan, 2,2-difluoro-2,5-dihydro-5,5-bis(trifluoromethyl)-, polymer with 1-[1-(1-butoxyethoxy)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-98-9 CMF C6 H2 F8 O

CRN 424825-97-8 CMF C16 H22 F6 O2

RN 424826-05-1 CAPLUS

CN 2,5-Furandione, polymer with 7-[(2-methoxyethoxy)methoxy]-7-(nonafluorobutyl)bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424826-04-0 CMF C15 H17 F9 O3

CM 2

CRN 108-31-6 CMF C4 H2 O3

RN 424826-07-3 CAPLUS

CN 2H-Pyran, 2-[[7-(heptafluoropropyl)bicyclo[2.2.1]hept-2-en-7-yl]oxy]tetrahydro-, polymer with 2,5-dihydro-2,2,5,5-tetrakis(trifluoromethyl)furan (9CI) (CA INDEX NAME)

CM 1

CRN 424826-06-2 CMF C15 H17 F7 O2

CRN 424825-90-1 CMF C8 H2 F12 O

IT 424826-62-0

RL: RCT (Reactant); RACT (Reactant or reagent) (monomer of high-mol. compds. for photoresists)

RN 424826-62-0 CAPLUS

CN Ethanone, 1-bicyclo[2.2.1]hept-2-en-1-yl-2,2,2-trifluoro- (9CI) (CA INDEX NAME)

RE.CNT 23 THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L5 ANSWER 3 OF 5 CAPLUS COPYRIGHT 2003 ACS on STN

AN 1994:81543 CAPLUS

DN 120:81543

TI Ion conductive polymer solid electrolytes

IN Armand, Michel; Sanchez, Jean Yves; Deroo, Daniel

PA Centre National de la Recherche Scientifique, Fr.; Hydro-Quebec

SO PCT Int. Appl., 22 pp.

CODEN: PIXXD2

DT Patent

LA French

FAN.CNT 1

FAN.	CNT	1														
	PAT	TENT 1	NO.		KII	ND.	DATE			APPLI	CATIC	N NO	٠.	DATE		
		- -	 ·								. – – – –		_	- -		
PI	WO	92160	028		A:	1	1992	0917		WO 19	92-FR	198		19920	0304	
		W :	CA,	JP,	US											
		RW:	ΑT,	BE,	CH,	DE,	DK,	ES,	FR,	GB, GR,	IT,	LU,	MC,	NL,	SE	
	FR	26737	769		A:	1	1992	0911		FR 19	91-27	15		19910	307	
	FR	26737	769		В:	1	1993	0618								
	ΕP	53149	92		A:	1	1993	0317		EP 19	92-90	7207		19920	304	
	ΕP	53149	92		B:	l.	1995	1004								
		R:	AT,	BE,	CH,	DE,	DK,	ES,	FR,	GB, GR,	IT,	LI,	LU,	MC,	NL,	SE
	JP	05506	6540		T	2	1993	0922		JP 19	92-50	6905		19920	0304	
	JP	34293	305		B2	2	2003	0722								

AT 128792	. E	19951015	AT 1992-907207	19920304
US 5350646	A	19940927	US 1992-945639	19921106
PRAI FR 1991-27	15 A	19910307		

19920304

W

The electrolytes are a solid soln. of .gtoreq.1 salts in a polymer where the transport and mobility of a metal cation Mn+ with valence n=1-5 is provided by .gtoreq.1 complex anion of formula [MZnYp]p- formed between an anionic ligand Z-, an anionic ligand Y-, and the cation Mn+ where p=1-3. The salt is A(MxZzYy) where A is a cation of valence p=1 or 2 and p=z+y-nx, permitting the coexistence of anions [MZnYp]p- and [MZnYp+1](p+1)- or [MZn+1Yp](p+1)- or the neutral species MZn. Examples included poly(ethylene oxide) which was mixed in soln. with CF3CO2Cs and (CF3CO2)2Ni forming a solid soln. contg. the complex Ni(CF3CO2)3-.

IT 151582-20-6D, metal complexes

RL: USES (Uses)

WO 1992-FR198

(polymers contg., as ionic conductive solid electrolytes)

RN 151582-20-6 CAPLUS

CN 4-Cyclopentene-1,3-dione, 2-(trifluoroacetyl)- (9CI) (CA INDEX NAME)

L5 ANSWER 4 OF 5 CAPLUS COPYRIGHT 2003 ACS on STN

AN 1989:25185 CAPLUS

DN 110:25185

TI **Polymer** chemistry. Part 1. Model compounds related to hexafluoropropene-vinylidene fluoride elastomer

AU Apsey, G. C.; Chambers, R. D.; Salisbury, M. J.; Moggi, G.

CS Dep. Chem., Univ. Durham, Durham, DH1 3LE, UK

SO Journal of Fluorine Chemistry (1988), 40(2-3), 261-82 CODEN: JFLCAR; ISSN: 0022-1139

DT Journal

LA English

AB Model compds. related to the title rubber were synthesized from telomers (CF3)2CF(CH2CF2)nI, by coupling and by fluorodeiodination reactions. These models, in reactions with bases, gave information relating to mechanisms of vulcanization of the **polymer** and indications of factors that limit its working life.

IT 116071-12-6P

RL: SPN (Synthetic preparation); PREP (Preparation) (prepn. of, as model for hexafluoropropene-vinylidene fluoride elastomer)

RN 116071-12-6 CAPLUS

CN Cyclopentene, 1,4,5,5-tetrafluoro-3,3-bis(trifluoromethyl)-2-[2,2,2-trifluoro-1-(trifluoromethyl)ethyl]- (9CI) (CA INDEX NAME)

L5 ANSWER 5 OF 5 CAPLUS COPYRIGHT 2003 ACS on STN

AN 1988:493667 CAPLUS

DN 109:93667

TI Antimony pentafluoride in the synthesis of novel fluoroalkene derivatives and a novel approach to conjugated polymers

AU Chambers, Richard D.; Salisbury, Martin; Apsey, Glenn; Holmes, Thomas F.; Modena, Silvana

CS Dep. Chem., Univ. Sci. Lab., Durham, DH1 3LE, UK

SO Journal of the Chemical Society, Chemical Communications (1988), (10), 679-80

CODEN: JCCCAT; ISSN: 0022-4936

DT Journal

LA English

AB SbF5-induced .beta.-eliminations of HF or HCl was remarkably effective in the prepn. of conjugated polymers from polyvinyl halides. When a thin film of poly(vinylidene fluoride) was exposed, under high vacuum, to SbF5 vapor at room temp., the film rapidly darkened and took on a lustrous black appearance; polytrifluoroethylene behaved similarly, but heating was required. A film of PVC went instantly black upon contact with SbF5 vapor.

IT 116071-12-6P

RL: FORM (Formation, nonpreparative); PREP (Preparation) (formation of, by cyclization of bis(trifluoromethyl)decafluoroctadien e, in presence of antimony pentafluoride)

RN 116071-12-6 CAPLUS

CN Cyclopentene, 1,4,5,5-tetrafluoro-3,3-bis(trifluoromethyl)-2-[2,2,2-trifluoro-1-(trifluoromethyl)ethyl]- (9CI) (CA INDEX NAME)

```
ANSWER 1 OF 2 CAPLUS COPYRIGHT 2003 ACS on STN
L10
     2003:301117 CAPLUS
AN
DN
     138:304711
ΤI
     Novel fluoropolymer, resist compositions containing the same, and novel
     fluoromonomers
     Araki, Takayuki; Ishikawa, Takuji; Koh, Meiten
IN
PA
     Daikin Industries, Ltd., Japan
SO
     PCT Int. Appl., 153 pp.
     CODEN: PIXXD2
DT
     Patent
LA
     Japanese
FAN.CNT 1
     PATENT NO.
                     KIND DATE
                                          APPLICATION NO. DATE
     ---------
                      _ _ _ _
                           -----
                                           -----
     WO 2003031487
                            20030417
                                          WO 2002-JP10242 20021002
PI
                     A1
         W: JP, KR, US
         RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT,
             LU, MC, NL, PT, SE, SK, TR
PRAI JP 2001-307823
                            20011003
                    Α
     JP 2002-54964
                            20020228
                      Α
     MARPAT 138:304711
OS
AΒ
     The present invention relates to a fluorocopolymer having aliph.
     monocyclic structures in the backbone chain, as represented by the general
     formula (M1)(M2a)(N) wherein structural unit (M1) is a unit derived from
     an ethylenic monomer having two or three carbon atoms and at least one
     fluorine atom; structural unit (M2a) is at least one kind of unit
     represented by the general formula I and forming an aliph. monocyclic
     structure in the backbone chain; and structural unit (N) is a unit derived
     from a monomer copolymerizable with structural units (M1) and (M2a), which
     comprises 1 to 99 mol% of structural units (M1), 1 to 99 mol% of
     structural units (M2a) and 0 to 98 mol% of structural units (N) and has a
     no.-av. mol. wt. of 500 to 1,000,000. In the formula I, R1 is at least
     one group selected from among divalent hydrocarbon groups which each have
     one to eight ring-constituting carbon atoms and may be substituted with
     hydrocarbyl or fluoroalkyl, and divalent hydrocarbon groups which each
     have an ether linkage with the sum of ring-constituting carbon and oxygen
     atoms ranging from 2 to 8 and may be substituted with hydrocarbyl or
     fluoroalkyl; R2 is alkylene having one to three ring-constituting carbon
     atoms; R3 and R4 are each independently alkylene having one or two carbon
     atoms; and n1, n2, and n3 are each independently 0 or 1. This
     fluorocopolymer exhibits excellent dry etching resistance and transparency
     in the vacuum UV region. Thus, 3.4 g cyclopentene and 10.0 g
     tetrafluoroethylene were reacted in HCFC 141b contg. bis(4-tert-
     butylcyclohexyl) peroxydicarbonate to give a 50:50 mol% copolymer with Mn
     5700.
IT
     509085-40-9P
     RL: IMF (Industrial manufacture); PRP (Properties); RCT (Reactant); TEM
     (Technical or engineered material use); PREP (Preparation); RACT (Reactant
     or reagent); USES (Uses)
        (prepn. of fluoropolymers or fluoromonomers useful for photoresist
        compns.)
RN
     509085-40-9 CAPLUS
CN
     2-Cyclopentene-1-methanol, .alpha.,.alpha.-bis(trifluoromethyl)-, polymer
     with tetrafluoroethene (9CI) (CA INDEX NAME)
     CM
          1
```

CRN

CMF

509085-39-6

C8 H8 F6 O

CRN 116-14-3 CMF C2 F4

IT 509085-40-9DP, hydrolyzed

RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (prepn. of fluoropolymers or fluoromonomers useful for photoresist compns.)

RN 509085-40-9 CAPLUS

CN 2-Cyclopentene-1-methanol, .alpha.,.alpha.-bis(trifluoromethyl)-, polymer with tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 509085-39-6 CMF C8 H8 F6 O

CM 2

CRN 116-14-3 CMF C2 F4

RE.CNT 2 THERE ARE 2 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L10 ANSWER 2 OF 2 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2002:353506 CAPLUS

DN 136:377479

TI High-molecular compounds for photoresists, monomeric compounds, photosensitive resin compositions, method for forming patterns with the compositions, and process for production of electronic components

IN Shida, Naomi; Ushirogouchi, Toru; Naito, Takuya

PA Kabushiki Kaisha Toshiba, Japan

SO PCT Int. Appl., 321 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

FAN.CNT 1

L MIN .	CIVI			•	
	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2002036646	A1	20020510	WO 2001-JP9567	20011031
	W: KR, US				
	JP 2002201219	A2	20020719	JP 2001-295012	20010926
PRAI	JP 2000-332358	Α	20001031		
	JP 2001-295012	Α	20010926		

OS MARPAT 136:377479

AB High-mol. compds. for photoresists, each having at least one skeleton represented by the general formula -RC(Rx1)2(ORx1), I, II, or III:
-RC(Rx1)2(ORx1) I II III(R = alicyclic skeleton; Rx1= electron-attracting group, H, monovalent org. group). The compds. shows small absorption towards .ltoreq.160 nm light and provides the fine resist pattern of nanometer size and of the high etching resistance.

IT 424825-88-7P 424825-93-4P 424825-96-7P 424825-99-0P 424826-05-1P 424826-07-3P

RL: SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(high-mol. compds. for photoresists)

RN 424825-88-7 CAPLUS

CN 2,5-Furandione, polymer with 3-ethenyltetrahydro-5-(2-tricyclo[3.3.1.13,7]dec-1-ylethyl)-2,2-bis(trifluoromethyl)furan and 1,3,3-tris(trifluoromethyl)-2-oxabicyclo[3.2.1]oct-6-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-87-6 CMF C20 H26 F6 O

$$F_3C$$
 CH_2-CH_2
 $H_2C=CH$

CM 2

CRN 424825-86-5 CMF C10 H7 F9 O

CRN 108-31-6 CMF C4 H2 O3

RN 424825-93-4 CAPLUS

CN 2H-Pyran, tetrahydro-2-[[7-(trifluoromethyl)bicyclo[2.2.1]hept-2-en-7-yl]oxy]-, polymer with 2,2,5,5-tetrafluoro-2,5-dihydrofuran (9CI) (CA INDEX NAME)

CM 1

CRN 424825-92-3 CMF C13 H17 F3 O2

CM 2

CRN 24565-48-8 CMF C4 H2 F4 O

RN 424825-96-7 CAPLUS

CN Furan, 2,5-dihydro-2,2,5,5-tetrakis(pentafluoroethyl)-, polymer with 1-[2,2,2-trifluoro-1-[(2-methoxyethoxy)methoxy]-1- (trifluoromethyl)ethyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-95-6 CMF C12 H2 F20 O

CM 2

CRN 424825-94-5 CMF C14 H18 F6 O3

RN 424825-99-0 CAPLUS

CN Furan, 2,2-difluoro-2,5-dihydro-5,5-bis(trifluoromethyl)-, polymer with 1-[1-(1-butoxyethoxy)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424825-98-9 CMF C6 H2 F8 O

CM 2

CRN 424825-97-8 CMF C16 H22 F6 O2

RN 424826-05-1 CAPLUS

CN 2,5-Furandione, polymer with 7-[(2-methoxyethoxy)methoxy]-7-(nonafluorobutyl)bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 424826-04-0 CMF C15 H17 F9 O3

CRN 108-31-6 CMF C4 H2 O3

RN 424826-07-3 CAPLUS

CN 2H-Pyran, 2-[[7-(heptafluoropropyl)bicyclo[2.2.1]hept-2-en-7-yl]oxy]tetrahydro-, polymer with 2,5-dihydro-2,2,5,5-tetrakis(trifluoromethyl)furan (9CI) (CA INDEX NAME)

CM 1

CRN 424826-06-2 CMF C15 H17 F7 O2

CM 2

CRN 424825-90-1 CMF C8 H2 F12 O

RE.CNT 23 THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

```
11 ANSWER 1 OF 2 CAPLUS COPYRIGHT 2003 ACS on STN
     2003:301117 CAPLUS
AN
DN
     138:304711
TΤ
     Novel fluoropolymer, resist compositions containing the same, and novel
     fluoromonomers
IN
     Araki, Takayuki; Ishikawa, Takuji; Koh, Meiten
PΑ
     Daikin Industries, Ltd., Japan
SO
     PCT Int. Appl., 153 pp.
     CODEN: PIXXD2
DT
     Patent
     Japanese
LΑ
FAN.CNT 1
                     KIND DATE
     PATENT NO.
                                         APPLICATION NO. DATE
     _____
                    ---- -----
                                         ______
     WO 2003031487
                         20030417
                                         WO 2002-JP10242 20021002
PΤ
                    A1
        W: JP, KR, US
        RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT,
            LU, MC, NL, PT, SE, SK, TR
PRAI JP 2001-307823
                    Α
                           20011003
     JP 2002-54964
                      Α
                           20020228
    MARPAT 138:304711
             THERE ARE 2 CITED REFERENCES AVAILABLE FOR THIS RECORD
             ALL CITATIONS AVAILABLE IN THE RE FORMAT
L11 ANSWER 2 OF 2 CAPLUS COPYRIGHT 2003 ACS on STN
    2002:353506 CAPLUS
AN
DN
    136:377479
ΤI
    High-molecular compounds for photoresists, monomeric compounds,
    photosensitive resin compositions, method for forming patterns
    with the compositions, and process for production of electronic components
IN
    Shida, Naomi; Ushirogouchi, Toru; Naito, Takuya
PΑ
    Kabushiki Kaisha Toshiba, Japan
SO
    PCT Int. Appl., 321 pp.
    CODEN: PIXXD2
DT
    Patent
LΑ
    Japanese
FAN.CNT 1
    PATENT NO.
                    KIND DATE
                                        APPLICATION NO.
                                                         DATE
     -----
                          -----
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                                         -----
                                                         -----
    WO 2002036646
PΤ
                     A1
                          20020510
                                         WO 2001-JP9567
                                                         20011031
        W: KR, US
    JP 2002201219
                     A2
                                         JP 2001-295012
                          20020719
                                                         20010926
PRAI JP 2000-332358
                     Α
                          20001031
    JP 2001-295012
                     Α
                          20010926
    MARPAT 136:377479
RE.CNT 23
             THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD
             ALL CITATIONS AVAILABLE IN THE RE FORMAT
```

```
L16 ANSWER 77 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
    2001:747183 CAPLUS
AN
DN
    135:310922
    Photoresist resin composition comprising novel
TI
    polysiloxane silicon-containing alicyclic compound
     Iwasawa, Haruo; Shimokawa, Tsutomu; Akihiro, Hayashi; Nishiyama, Satoru
IN
PΑ
    JSR Corporation, Japan
SO
    Eur. Pat. Appl., 109 pp.
    CODEN: EPXXDW
חת
    Patent
    English
LA
FAN.CNT 1
                     KIND DATE
                                          APPLICATION NO. DATE
     PATENT NO.
                     ----
                          -----
                                          -----
                                                          -----
     ------------
                                                          20010405
    EP 1142928
                      A1
                           20011010
                                          EP 2001-108625
        R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
            IE, SI, LT, LV, FI, RO
```

ΡI JP 2001288268 A2 20011016 JP 2000-107207 20000407 JP 2002105086 A2 20020410 JP 2000-291089 20000925 JP 2002128788 A2 20020509 JP 2000-318752 20001019 US 2001041769 Α1 20011115 US 2001-824224 20010403 B2 20030311 US 6531260 PRAI JP 2000-107207 Α 20000407 JP 2000-291089 Α 20000925 20001019 Α JP 2000-318752

AB A novel polysiloxane having the structural units of the following formula I, II and III (A1, A2 = acid-dissociable monovalent org. group, R1 = H, monovalent (halogenated) hydrocarbon, halogen, amino, R2 = monovalent (halogenated) hydrocarbon group, halogen) is disclosed. A method of prepg. such a polysiloxane, a silicon-contg. alicyclic compd. providing this polysiloxane, and a radiation-sensitive resin compn. comprising this polysiloxane are also provided. The polysiloxane is useful as a resin component for a resist material, effectively senses radiation with a short wavelength (157-248 nm), exhibits high transparency to radiation and superior dry etching properties, and excels in basic resist properties required for resist materials such as high sensitivity, resoln., developability, etc.

IT 196314-61-1

RL: RCT (Reactant); RACT (Reactant or reagent)
 (in prepn. of silicon-contg. alicyclic compd.)

RN 196314-61-1 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-(9CI) (CA INDEX NAME)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L16 ANSWER 78 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2001:636379 CAPLUS

DN 135:218727

TI Resist materials for 157-nm lithography

IN Fedynyshyn, Theodore H.

PA Massachusetts Institute of Technology, Inc., USA

SO PCT Int. Appl., 43 pp.

CODEN: PIXXD2

DTPatent LA English

FAN.CNT 1

APPLICATION NO. DATE PATENT NO. KIND DATE ______ ----

ΡI WO 2001063362 A2 20010830 WO 2

```
ANSWER 78 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
L16
AN
     2001:636379 CAPLUS
DN
     135:218727
ТT
     Resist materials for 157-nm lithography
     Fedynyshyn, Theodore H.
TN
PΑ
     Massachusetts Institute of Technology, Inc., USA
SO
     PCT Int. Appl., 43 pp.
     CODEN: PIXXD2
DT
     Patent
     English
LA
FAN.CNT 1
     PATENT NO.
                      KIND DATE
                                           APPLICATION NO.
                                                           DATE
                      _ _ _ _
                           _____
                                           -----
     ______
                                           WO 2001-US5907
                                                            20010226
     WO 2001063362
                       A2
                            20010830
PΙ
     WO 2001063362
                      Α3
                            20020307
         W: CA, JP
         RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL,
             PT, SE, TR
     US 6468712
                       В1
                            20021022
                                           US 2000-513792
                                                            20000225
                                           EP 2001-911149
                                                            20010226
     EP 1257880
                       A2
                            20021120
             AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
             IE, FI, CY, TR
PRAI US 2000-513792
                            20000225
                       Α
     WO 2001-US5907
                       W
                            20010226
     The invention relates to photoresist materials useful in
     microlithog, and to improved materials and methods for pattern formation
     on semiconductor wafers. A radiation sensitive resin compn.
     including a photo-acid generator and an aliph. polymer having
     .gtoreq.1 electron withdrawing groups adjacent to or attached to a C atom
     bearing a protected hydroxyl group, wherein the protecting group is labile
     in the presence of in situ generated acid is described.
                                                              The radiation
     sensitive resin compn. can be used as a resist suitable for
     image transfer by plasma etching and enable 1 to obtain an etching image
     having high precision with high reproducibility with a high degree of
     resoln. and selectivity.
IT
     357397-06-9D, functional-group protected 357397-07-0D,
     functional-group protected 357397-08-1D, functional-group
     protected 357397-09-2D, functional-group protected
     RL: DEV (Device component use); POF (Polymer in formulation); TEM
     (Technical or engineered material use); USES (Uses)
        (pos. photoresist compn. for 157-nm lithog. using)
RN
     357397-06-9 CAPLUS
     Bicyclo[2.2.1] hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-,
CN
     polymer with tetrafluoroethene (9CI) (CA INDEX NAME)
     CM
          ٦
    CRN
         196314-61-1
     CMF C11 H12 F6 O
            OH
             CF3
            CF<sub>3</sub>
```

CRN 116-14-3 CMF C2 F4

RN 357397-07-0 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-, homopolymer (9CI) (CA INDEX NAME)

CM 1

·CRN 196314-61-1 CMF C11 H12 F6 O

RN 357397-08-1 CAPLUS

CN 2-Propenoic acid, 1,1-dimethylethyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1 CMF C11 H12 F6 O

CM 2

CRN 1663-39-4 CMF C7 H12 O2

RN 357397-09-2 CAPLUS

CN 2,5-Furandione, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2 .2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1 CMF C11 H12 F6 O

CRN 108-31-6 CMF C4 H2 O3

```
ANSWER 82 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
L16
AN
     2001:380920 CAPLUS
     134:359532
DN
     Nitrile/fluoroalcohol-containing photoresists and associated processes for
ΤI
     microlithography
     Fryd, Michael; Schadt, Frank Leonard, III; Periyasamy, Mookkan
IN
     E.I. Du Pont De Nemours and Company, USA
PΑ
     PCT Int. Appl., 40 pp.
SO
     CODEN: PIXXD2
DT
     Patent
     English
LA
FAN.CNT 1
                      KIND DATE
                                           APPLICATION NO. DATE
     PATENT NO.
     _____
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                           _____
                                           -----
PΙ
     WO 2001037047
                      A2
                            20010525
                                           WO 2000-US31136 20001114
     WO 2001037047
                      A3
                            20020328
            AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN,
             CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR,
             HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT,
             LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU,
             SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN,
             YU, ZA, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM
         RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW, AT, BE, CH, CY,
            DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR, BF,
             BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG
                          20020918
                                          EP 2000-978579
                                                          20001114
     EP 1240554
                      A2
            AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
             IE, SI, LT, LV, FI, RO, MK, CY, AL, TR
                      B1
                           20030107
                                           US 2000-714782
                                                            20001116
PRAI US 1999-166035P
                       Р
                            19991117
     WO 2000-US31136
                      W
                            20001114
AB
     The invention pertains to photoimaging and use of photoresists (pos. - and
     neg.-working) for imaging in the prodn. of semiconductor devices and to
     photoresists contg. polymer compns. having high UV transparency,
     particularly at short wavelengths, e. g., 157 nm or 193 nm, that are
     useful as base resins in resists and potentially, in many other
     applications. Nitrile/fluoroalc.-contg. photoresists and assocd.
     processes for microlithog. are described. These photoresists are
     comprised of a fluoroalc. functional group and a nitrile-contg. compd.
     which together simultaneously impart high UV transparency and development
     in basic media to these materials. The materials have high UV
     transparency, particularly at short wavelengths, e.g., 157 nm, which makes
     them highly useful for lithog. at these short wavelengths.
     339265-99-5P 339266-00-1P 339266-01-2P
TΤ
     RL: NUU (Other use, unclassified); PNU (Preparation, unclassified); POF
     (Polymer in formulation); PREP (Preparation); USES (Uses)
        (prepn. of polymers for nitrile/fluoroalc.-contg. compns. for
        photoresists having high UV transparency)
RN
     339265-99-5 CAPLUS
     2-Propenoic acid, 2-methyl-, polymer with 2-propenenitrile and
CN
     5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]bicyclo[2
     .2.1]hept-2-ene (9CI) (CA INDEX NAME)
     CM
          1
     CRN
         305815-64-9
         C13 H16 F6 O3
     CMF
```

CRN 107-13-1 CMF C3 H3 N

 $H_2C = CH - C = N$

CM 3

CRN 79-41-4 CMF C4 H6 O2

$$\begin{array}{c} \text{CH}_2 \\ || \\ \text{Me-C-CO}_2 \text{H} \end{array}$$

RN 339266-00-1 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1,1-dimethylethyl ester, polymer with 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-2-propanol and 2-propenenitrile (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 2

CRN 585-07-9 CMF C8 H14 O2

CM 3

 $H_2C = CH - C = N$

RN 339266-01-2 CAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with 1,1-dimethylethyl 2-methyl-2-propenoate, 2-propenenitrile and 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-64-9 CMF C13 H16 F6 O3

CM 2

CRN 585-07-9 CMF C8 H14 O2

CM 3

CRN 107-13-1 CMF C3 H3 N

 $H_2C = CH - C = N$

CM 4

CRN 79-41-4 CMF C4 H6 O2

$$^{\text{CH}_2}_{||}_{\text{Me-C-CO}_2\text{H}}$$

IT 305815-63-8P 305815-64-9P

RL: NUU (Other use, unclassified); RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent); USES (Uses)

(prepn. of, for nitrile/fluoroalc.-contg. **polymer** compns. for photoresists having high UV transparency)

RN 305815-63-8 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro- (9CI) (CA INDEX NAME)

RN 305815-64-9 CAPLUS

CN Bicyclo[2.2.1]hept-2-ene, 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]- (9CI) (CA INDEX NAME)

L16 ANSWER 83 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:870325 CAPLUS

DN 134:214846

TI 157 nm resist materials: Progress report

AU Brodsky, Colin; Byers, Jeff; Conley, Will; Hung, Raymond; Yamada, Shintaro; Patterson, Kyle; Somervell, Mark; Trinque, Brian; Tran, H. V.; Cho, Sungseo; Chiba, Takashi; Lin, Shang-Ho; Jamieson, Andrew; Johnson, Heather; Vander Heyden, Tony; Willson, C. Grant

CS Departments of Chemistry and Chemical Engineering, The University of Texas at Austin, Austin, TX, 78735, USA

SO Journal of Vacuum Science & Technology, B: Microelectronics and Nanometer Structures (2000), 18(6), 3396-3401 CODEN: JVTBD9; ISSN: 0734-211X

PB American Institute of Physics

DT Journal

LA English

AB Many semiconductor device manufacturers plan to make products with 157 nm lithog. beginning in 2004. There is, at this time, no functional photoresist suitable for 157 nm exposure. Developing resist materials for 157 nm lithog. is particularly challenging since water, oxyg

L16 ANSWER 83 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:870325 CAPLUS

DN 134:214846

TI 157 nm resist materials: Progress report

AU Brodsky, Colin; Byers, Jeff; Conley, Will; Hung, Raymond; Yamada, Shintaro; Patterson, Kyle; Somervell, Mark; Trinque, Brian; Tran, H. V.; Cho, Sungseo; Chiba, Takashi; Lin, Shang-Ho; Jamieson, Andrew; Johnson, Heather; Vander Heyden, Tony; Willson, C. Grant

CS Departments of Chemistry and Chemical Engineering, The University of Texas at Austin, Austin, TX, 78735, USA

SO Journal of Vacuum Science & Technology, B: Microelectronics and Nanometer Structures (2000), 18(6), 3396-3401 CODEN: JVTBD9; ISSN: 0734-211X

PB American Institute of Physics

DT Journal

LA English

Many semiconductor device manufacturers plan to make products with 157 nm AB lithog. beginning in 2004. There is, at this time, no functional photoresist suitable for 157 nm exposure. Developing resist materials for 157 nm lithog. is particularly challenging since water, oxygen, and even polyethylene are strongly absorbing at this wavelength. A modular approach to the design of a single layer resist for 157 nm has been undertaken. In this approach, the resist has been conceptually segmented into four functional modules: an acidic group, an acid labile protecting group, an etch resistant moiety, and a polymer backbone. Each of these modules has an assigned function and each must be transparent at 157 nm. Progress has been made toward finding candidate structures for each of these modules. The authors have demonstrated that acidic bistrifluoromethylcarbinols are very transparent at 157 nm and function efficiently in chem. amplified resists with both high and low activation energy protecting groups. Judicious incorporation of fluorine in acrylates and alicyclics has provided etch resistant polymers with greatly improved transparency at 157 nm. In particular, esters of poly(.alpha.-trifluromethylacrylic acid) are far more transparent than their protio analogs. The Diels-Alder adducts derived from reaction of these and other fluorinated alkenes with cyclopentadiene offer a route to a wide range of alicyclic monomers that show great promise as transparent, etch resistant platforms for the design of 157 nm resists. Polymers of this sort with absorbance below 2 per .mu.m are reported.

IT 302580-86-5 328114-62-1

RL: PRP (Properties)

(design of photoresist materials for 157 nm lithog.)

RN 302580-86-5 CAPLUS

CN Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 196314-63-3 CMF C16 H20 F6 O3

RN 328114-62-1 CAPLUS

CN 2,5-Furandione, polymer with 5-[2-(ethoxymethoxy)-3,3,3-trifluoro-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 328114-61-0 CMF C14 H18 F6 O2

CM 2

CRN 108-31-6 CMF C4 H2 O3

RE.CNT 19 THERE ARE 19 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L16 ANSWER 84 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:806346 CAPLUS

DN 134:200397

TI Polymers for 157-nm photoresist applications: a progress report

AU Patterson, Kyle; Yamachika, Miko; Hung, Raymond J.; Brodsky, Colin J.; Yamada, Shintaro; Somervell, Mark H.; Osborn, Brian; Hall, Daniel; Dukovic, Gordana; Byers, Jeffrey; Conley, Willard; Willson, C. Grant

CS Dep. Chemistry and Chem. Eng., The Univ. Texas at Austin, Austin, TX, USA

SO Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 365-374

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DT Journal

LA English

AB Finding materials that offer the all of the characteristics required of photoresist matrix resin polymers while trying to maintain a high level of transparency at 157 nm is a daunting challenge. To simplify this task, the authors have broken the design of these polymers down into subunits, each of which was responsible for a required function in the final material. In addn., the authors have begun collecting gas-phase VUV spectra of these potential subunits to measure their individual absorbance contributions. Progress on developing materials for each of these subunits were presented along with plans for future studies.

IT 328114-62-1

RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)

(model polymer; design of polymers and their subunits for 157-nm photoresist applications)

RN 328114-62-1 CAPLUS

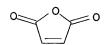
2,5-Furandione, polymer with 5-[2-(ethoxymethoxy)-3,3,3-trifluoro-2-CN (trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 328114-61-0 CMF C14 H18 F6 O2

CM 2

CRN 108-31-6 CMF C4 H2 O3



RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

ANSWER 85 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN L16

AN2000:806336 CAPLUS

DN 134:214824

TIUsing alicyclic polymers in top surface imaging systems to reduce line-edge roughness

ΝA Somervell, Mark H.; Fryer, David S.; Osborn, Brian; Patterson, Kyle; Cho, Sungseo; Byers, Jeffrey D.; Willson, C. Grant

Univ. of Texas at Austin, Dallas, TX, USA CS

SO. Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 270-282

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DTJournal

LA English

AB Top surface imaging (TSI) systems based on vapor phase silylation have been investigated for use at a variety of wavelengths. This approach to generating high aspect ratio, high resoln. images held great promise particularly for 193 nm and extreme-UV lithog. applications. Several 193 nm TSI systems have been described that produce very high resoln. (low kfactor) images with wide process latitude. However, because of the line edge roughness assocd. with the final images, TSI systems have fallen from favor. In fact, top surface imaging and line edge roughness have become synonymous in the minds of most. Most of the 193 nm TSI systems are based on poly(p-hydroxystyrene) resins. These polymers have an unfortunate combination of properties that limit their utility in this application. These limiting properties include (1) high optical d., (2) poor silylation contrast, and (3) low glass transition temp. of the silylated material. These shortcomings are related to inherent polymer characteristics and are responsible for the pronounced line edge roughness in the poly(p-hydroxystyrene) systems. The authors synthesized certain

alicyclic polymers that have higher transparency and higher glass

transition temps. Using these polymers, the authors demonstrated the ability to print high resoln. features with very smooth sidewalls. This paper describe the synthesis and characterization of the polymers and their application to top surface imaging at 193 nm. The anal. that was used to tailor the processing and the **polymer**'s phys. properties to achieve optimum imaging is also described.

IT 214079-69-3

RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)

(lithog. performance of alicyclic-polymer based chem. amplified photoresists in top surface imaging for redn. of line-edge roughness)

RN 214079-69-3 CAPLUS

CN Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1 (trifluoromethyl)ethyl 1,1-dimethylethyl ester, polymer with sulfur
 dioxide, alternating (9CI) (CA INDEX NAME)

CM 1

CRN 196314-63-3 CMF C16 H20 F6 O3

CM 2

CRN 7446-09-5 CMF O2 S

o = s = o

RE.CNT 17 THERE ARE 17 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L16 ANSWER 86 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:806316 CAPLUS

DN 134:200382

TI Negative-tone 193-nm resists

AU Cho, Sungseo; Vander Heyden, Anthony; Byers, Jeffrey D.; Willson, C. Grant

CS Univ. of Texas at Austin, Austin, TX, USA

SO Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 62-73

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DT Journal

LA English

AB A great deal of progress has been made in the design of single layer pos. tone resists for 193 nm lithog. Com. samples of such materials are now available from many vendors. The patterning of certain levels of devices profits from the use of neg. tone resists. There have been several reports of work directed toward the design of neg. tones resists for 193

nm exposure but, none have performed as well as the pos. tone systems. Polymers with alicyclic structures in the backbone have emerged as excellent platforms from which to design pos. tone resists for 193 nm exposure. The authors report the adaptation of this class of polymers to the design of high performance neg. tone 193 nm resists. New systems have been prepd. that are based on a polarity switch mechanism for modulation of the dissoln. rate. The systems are based on a polar, alicyclic polymer backbone that includes a monomer bearing a glycol pendant group that undergoes the acid catalyzed pinacol rearrangement upon exposure and bake to produce the corresponding less polar ketone. This monomer was copolymd. with maleic anhydride and a norbornene bearing a bis-trifluoromethylcarbinol. The rearrangement of the copolymer was monitored by FT-IR as a function of temp. The synthesis of the norbornene monomers will be presented together with characterization of copolymers of these monomers with maleic anhydride. The lithog. performance of the new resist system will also be presented.

IT 327610-81-1P

RL: PRP (Properties); SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(photoresist for 193 nm lithog. contg. terpolymer of maleic anhydride and norbornene with bis-trifluoromethylcarbinol and norbornene with glycol pendant group that undergoes acid catalyzed pinacol rearrangement)

RN 327610-81-1 CAPLUS

2,5-Furandione, polymer with 1-bicyclo[2:2.1]hept-5-en-2-yl-2,3-dimethyl-2,3-butanediol and .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CN

CRN 327610-80-0 CMF C13 H22 O2

CM 2

CRN 196314-61-1 CMF C11 H12 F6 O

CM 3

CRN 108-31-6 CMF C4 H2 O3

IT 196314-61-1P RL: RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent) (polymn. with maleic anhydride and (dihydroxydimethylbutyl)bicyclo[2.2. 1]heptene in synthesis of polymer photoresists for 193 nm lithog.) 196314-61-1 CAPLUS RN -Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-CN (CA INDEX NAME) OH CF3 RE.CNT 29 THERE ARE 29 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT L16 ANSWER 87 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN ΑN 2000:790750 CAPLUS DN 133:357252 ΤI Fluorinated polymers, photoresists and processes for microlithography Feiring, Andrew Edward; Feldman, Jerald IN E.I. Du Pont De Nemours and Company, USA PA SO PCT Int. Appl., 69 pp. CODEN: PIXXD2 DT · Patent LAEnglish

FAN.CNT 1 PATENT NO. KIND DATE

APPLICATION NO. DATE PΤ WO 2000067072 **A**1 20001109 WO 2000-US11539 20000428 AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM RW: GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW, AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG EP 1183571 20020306 EP 2000-928563 20000428 A1 AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO JP 2000-615852 JP 2002543469 T2 20021217 20000428 PRAI US 1999-132373P P 19990504 WO 2000-US11539 W 20000428

AB Fluorinated polymers, photoresists and assocd. processes for microlithog. are described. These polymers and photoresists are comprised of a fluoroalc. functional group which simultaneously imparts high UV transparency and developability in basic media to these materials. materials of this invention have high UV transparency, particularly at short wavelengths, e.g. 157 nm, which makes them highly useful for lithog. at these short wavelengths.

IT 305815-63-8P 305815-64-9P RL: RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent)

(fluorinated polymers, photoresists and processes for microlithog.)

RN 305815-63-8 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro- (9CI) (CA INDEX NAME)

RN 305815-64-9 CAPLUS

CN Bicyclo[2.2.1]hept-2-ene, 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]- (9CI) (CA INDEX NAME)

IT 305815-68-3P 305815-71-8P 305815-78-5P

RL: SPN (Synthetic preparation); PREP (Preparation)

(fluorinated polymers, photoresists and processes for microlithog.)

RN 305815-68-3 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-, polymer with bicyclo[2.2.1]hept-2-ene and tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 2

CRN 498-66-8 CMF C7 H10



CRN 116-14-3 CMF C2 F4

RN 305815-71-8 CAPLUS

CN Bicyclo[2.2.1]hept-2-ene, 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]-, polymer with bicyclo[2.2.1]hept-2-ene and tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-64-9 CMF C13 H16 F6 O3

CM 2

CRN 498-66-8 CMF C7 H10



CM 3

CRN 116-14-3 CMF C2 F4

RN 305815-78-5 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8

IT 305815-72-9P 305815-73-0P

RL: SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(fluorinated polymers, photoresists and processes for microlithog.)

RN 305815-72-9 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-, polymer with tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 2

CRN 116-14-3 CMF C2 F4

RN 305815-73-0 CAPLUS

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-, polymer with tetrafluoroethene and 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-64-9 CMF C13 H16 F6 O3

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 3

CRN 116-14-3 CMF C2 F4

RE.CNT 4 THERE ARE 4 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L16 ANSWER 88 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:711711 CAPLUS

DN 134:107878

TI Study of the fundamental contributions to line edge roughness in a 193 nm, top surface imaging system

AU Somervell, Mark H.; Fryer, David S.; Osborn, Brian; Patterson, Kyle; Byers, Jeffrey; Willson, C. Grant

CS Department of Chemical Engineering, The University of Texas at Austin, Austin, TX, 78731, USA

SO Journal of Vacuum Science & Technology, B: Microelectronics and Nanometer Structures (2000), 18(5), 2551-2559
CODEN: JVTBD9; ISSN: 0734-211X

PB American Institute of Physics

DT Journal

LA English

AB Top surface imaging systems based on vapor phase silylation have been investigated for use at a variety of wavelengths. This approach to generate high aspect ratio, high resoln. images held great promise particularly for 193 nm and extreme-UV lithog. applications. Several 193 nm top surface imaging (TSI) systems have been described that produce very high resoln. (low k factor) images with wide process latitude. However, because of the line edge roughness assocd. with the final images, TSI systems have fallen from favor. In fact, TSI does not appear in the strategy or plan for any imaging technol. at this time. Most of the 193 nm TSI systems that have been studied are based on poly(p-hydroxystyrene) resins. These polymers have an unfortunate combination of properties that limit their utility in this application. These limiting properties include (1) high optical d., (2) poor silylation contrast, and (3) low glass transition temp. of the silylated material. These shortcomings are related to inherent polymer characteristics and are responsible for the pronounced line edge roughness in the poly(p-hydroxystyrene) systems. The authors have synthesized certain alicyclic polymers that have higher transparency and higher glass transition temps. Using these polymers, we have demonstrated the ability to print high resoln. features

with very smooth sidewalls. This article describes the synthesis and characterization of the polymers, their application to top surface imaging at 193 nm, and the anal. that was used to tailor the processing and the **polymer's** phys. properties to achieve optimum imaging.

IT 214079-69-3

RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(factors contributing to **photoresist** line edge roughness in photolithog. surface imaging systems based on vapor phase silylation) 214079-69-3 CAPLUS

CN Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester, polymer with sulfur dioxide, alternating (9CI) (CA INDEX NAME)

CM 1

RN

CRN 196314-63-3 CMF C16 H20 F6 O3

CM 2

CRN 7446-09-5 CMF 02 S

o = s = o

RE.CNT 22 THERE ARE 22 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L16 ANSWER 89 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 1997:582361 CAPLUS

DN 127:270389

TI Synthesis and preliminary evaluation of substituted poly(norbornene sulfones) for 193 nm lithography

AU Ito, Hiroshi; Seehof, Norbert; Sato, Rikiya

CS IBM Almaden Research Center, San Jose, CA, 95120, USA

SO Polymeric Materials Science and Engineering (1997), 77, 449-450 CODEN: PMSEDG; ISSN: 0743-0515

PB American Chemical Society

DT Journal

LA English

AB The quest for higher resoln. continues in the microelectronics industry, which is currently shifting from i-line (365 nm) to deep UV (248 nm, KrF excimer laser) lithog. for manuf. of 256 megabit memory and related logic devices requiring 0.25 .mu.m resoln. This transition has been made possible by the revolutionary resist systems known as chem. amplification resists. In order to achieve even higher resoln. for a next generation device program, further shift to 193 nm (ArF excimer laser) has become a major thrust recently. Although the imaging mechanism of choice is most likely to be acid-catalyzed deprotection for pos. imaging in ArF lithog.

as is the case with KrF, polymer backbone structures require a total departure from the current phenolic systems. Arom. polymers cannot be used at the ArF excimer laser wavelength due to their excessive absorption. Thus, poly-methacrylates have been the dominant polymer backbone structure with a pendant bi-alicyclic group providing dry etch resistance. Excellent dry etch resistance of main chain alicyclic polymers such as polynorbornene has recently prompted efforts in development of chem. amplified resists based on such back bone structures. Since radical polymn. is still the most practical method of polymer prepn., we have decided to investigate alternating radical copolymn. of substituted norbornenes with sulfur dioxide. While the phenolic OH group has been the primary base-solubilizing functional group employed in the 248 nm resist design, the 193 nm resists have been exclusively based on carboxylic acid, which provides extremely fast dissoln. rates in aq. base, necessitating use of a non-std. weak aq. base developer. Thus, another goal we set forth was to identify a new base-solubilizing group which could be incorporated in 193 nm resists.

IT 196314-63-3P

CN

RL: PNU (Preparation, unclassified); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent)

(synthesis and preliminary evaluation of substituted poly(norbornene sulfones) for 193 nm lithog.)

RN 196314-63-3 CAPLUS

> Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester (9CI) (CA INDEX NAME)

IT196314-66-6P 196314-69-9P

> RL: PRP (Properties); SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(synthesis and preliminary evaluation of substituted poly(norbornene sulfones) for 193 nm lithog.)

RN 196314-66-6 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-carboxylic acid, 1,1-dimethylethyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol and sulfur dioxide (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1 CMF C11 H12 F6 O

CRN 154970-45-3 CMF C12 H18 O2

CM 3

CRN 7446-09-5 CMF 02 S

o = s = 0

RN 196314-69-9 CAPLUS

CN Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester, polymer with sulfur dioxide (9CI) (CA INDEX NAME)

CM 1

CRN 196314-63-3 CMF C16 H20 F6 O3

CM 2

CRN 7446-09-5 CMF 02 S

o = s = 0

IT 196314-61-1

RL: RCT (Reactant); RACT (Reactant or reagent)
 (synthesis and preliminary evaluation of substituted poly(norbornene
 sulfones) for 193 nm lithog.)

RN 196314-61-1 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-(9CI) (CA INDEX NAME)

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L16 ANSWER 68 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
     2001:918945 CAPLUS
AN
     136:45683
DN
ΤI
     Radiation-sensitive resin composition for chem. amplified resist
TN
     Nishimura, Yukio; Yamahara, Noboru; Yamamoto, Masafumi; Kajita, Toru;
     Shimokawa, Tsutomu; Ito, Hiroshi
     JSR Corporation, Japan; International Business Machines Corporation
PΑ
     Eur. Pat. Appl., 63 pp.
SO
     CODEN: EPXXDW
DT
     Patent
     English
LA
FAN.CNT 1
                      KIND DATE
                                           APPLICATION NO. DATE
     PATENT NO.
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                            ---<del>-</del>---
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                            20011219
                                           EP 2001-114503
                                                            20010615
PΙ
     EP 1164434
                      A2
         R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
             IE, SI, LT, LV, FI, RO
     JP 2002072484
                      A2
                            20020312
                                           JP 2001-108824
                                                             20010406
     US 2002009668
                       Α1
                            20020124
                                         US 2001-879894
                                                             20010614
     CN 1332205
                       Α
                            20020123
                                           CN 2001-124927
                                                             20010615
PRAI JP 2000-182297
                       Α
                            20000616
     JP 2001-108824
                       Α
                            20010406
os
     MARPAT 136:45683
    A radiation-sensitive resin compn. comprising an acid-labile
    group-contg. resin and a photoacid generator is disclosed.
     resin has a structure of X1R2COR1 (R1 = H, monovalent acid-labile
     group, C1-6 alkyl which does not have an acid-labile group, C2-7
     alkylcarbonyl which does not have an acid-labile group; X1 = C1-4
     fluorinated alkyl; and R2 = H, C1-10 alkyl, C1-10 fluorinated alkyl).
     resin compn. exhibits high transmittance of radiation, high
     sensitivity, resoln., and pattern shape, and is useful as a chem.
     amplified resist in producing semiconductors at a high yield.
IT
     370099-14-2P 370102-83-3P 380886-62-4P
     380886-63-5P 380886-66-8P 380886-68-0P
     380886-69-1P 380886-74-8DP, hydrogenated
     380886-74-8P 380886-75-9DP, hydrogenated
     380886-78-2P 380886-79-3P 380886-80-6P
     380886-81-7P 380886-82-8P 380886-83-9P
     RL: SPN (Synthetic preparation); TEM (Technical or engineered material
     use); PREP (Preparation); USES (Uses)
        (acid-labile group-contg. resin for radiation-sensitive
        resist compn.)
RN
     370099-14-2 CAPLUS
CN
     Bicyclo[2.2.1]hept-5-ene-2-carboxylic acid, 1,1-dimethylethyl ester,
     polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-
     2-ethanol (9CI) (CA INDEX NAME)
     CM
          1
     CRN
         196314-61-1
     CMF C11 H12 F6 O
            OH
```

CF₃

CF3

CRN 154970-45-3 CMF C12 H18 O2

RN 370102-83-3 CAPLUS

CN Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 196314-63-3 CMF C16 H20 F6 O3

CM 2

CRN 196314-61-1 CMF C11 H12 F6 O

RN 380886-62-4 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-carboxylic acid, 1-bicyclo[2.2.1]hept-2-yl-1-methylethyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 380886-61-3 CMF C18 H26 O2

CRN 196314-61-1 CMF C11 H12 F6 O

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L16 ANSWER 74 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
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AN 2001:791924 CAPLUS

DN 135:336912

TI Polymer having fluorinated maleic acid-type units, photoresist material, and patterning of the photoresist

IN Hatakeyama, Jun; Watanabe, Atsushi; Harada, Yuji

PA Shin-Etsu Chemical Industry Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 28 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

4 4 114	. О.1. 1							
	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE			
			-					
ΡI	JP 2001302735	A2	20011031	JP 2001-31743	20010208			
	US 2001038969	A1	20011108	US 2001-783446	20010215			
	US 6579658	B2	20030617					
PRA:	I JP 2000-40190	Α	20000217					
	JP 2000-40193	Α	20000217					

AB The polymer involves fluorinated maleic anhydride- or maleimide-derived repeating units. The photoresist material contains the polymer. A chem. amplified photoresist contg. the polymer, an org. solvent, an acid-generating agent, and a basic compd. is also claimed. The photoresist material is applied on a substrate, heated, exposed to high-energy beam or electron beam at .ltoreq.300 nm through a photomask, and developed optionally after heating. The photoresist material, showing high sensitivity F2 excimer laser, is suitable for fine processing in semiconductor device fabrication.

IT 370566-02-2P 370566-03-3P 370566-09-9P 370566-10-2P

RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(photoresist contg. polymer involving fluorinated
maleic anhydride- or maleimide-derived repeating units)

RN 370566-02-2 CAPLUS

CN 2,5-Furandione, 3,4-difluoro-, polymer with 5-[2-(2-ethoxyethoxy)-3,3,3-trifluoro-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 370566-01-1 CMF C15 H20 F6 O2

CM '2

CRN 669-78-3 CMF C4 F2 O3

RN 370566-03-3 CAPLUS

CN 2-Propenoic acid, 2-(trifluoromethyl)-, 1-ethylcyclopentyl ester, polymer with 3,4-difluoro-2,5-furandione and 5-[2-(2-ethoxyethoxy)-3,3,3-trifluoro-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 370566-01-1 CMF C15 H20 F6 O2

CM 2

CRN 357294-14-5 CMF C11 H15 F3 O2

CM 3

CRN 669-78-3 CMF C4 F2 O3

CN

RN 370566-09-9 CAPLUS

1H-Pyrrole-2,5-dione, 3,4-difluoro-1-methyl-, polymer with 5-[2-(2-ethoxyethoxy)-3,3,3-trifluoro-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 370566-01-1 CMF C15 H20 F6 O2

CRN 56154-82-6 CMF C5 H3 F2 N O2

RN 370566-10-2 CAPLUS

CN 2-Propenoic acid, 2-(trifluoromethyl)-, 1-ethylcyclopentyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol and 3,4-difluoro-1-methyl-1H-pyrrole-2,5-dione (9CI) (CA INDEX NAME)

CM 1

CRN 357294-14-5 CMF C11 H15 F3 O2

CM 2

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L20 ANSWER 8 OF 8 CAPLUS COPYRIGHT 2003 ACS on STN
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AN 2001:747183 CAPLUS

DN 135:310922

TI Photoresist resin composition comprising novel polysiloxane silicon-containing alicyclic compound

IN Iwasawa, Haruo; Shimokawa, Tsutomu; Akihiro, Hayashi; Nishiyama, Satoru

PA JSR Corporation, Japan

SO Eur. Pat. Appl., 109 pp.

CODEN: EPXXDW

DT Patent

LA English

FAN.CNT 1

	PATENT NO.			KI	ND	DATE			API	PLIC	ATIC	ON NO	Ο.	DATE				
	EP 1142928						EP 2001-108625											
ΡI			A1 20011010			20010405												
		R:	AT,	BE,	CH,	DE,	DΚ,	ES,	FR,	GB, C	GR,	IT,	LI,	LU,	NL,	SE,	MC,	PT,
			IE,	SI,	LT,	LV,	FΙ,	RO										
	JP	2001	28826	58	A:	2	2001	1016		JP	200	0-10	720	7	2000	0407		
	JP	2002	10508	36	A:	2	2002	0410		JP	200	0-29	91089	€	2000	0925		
	JP	2002	002128788		A:	2	2002	0509		JP	200	0-3	L8752	2	2000	1019		
	US	2001	1041769		A	1	2001	1115		US	200	1-82	24224	1	2001	0403		
	US	6531260			B	2	2003	0311										
PRAI	JP	2000	-1072	207	Α		2000	0407										
	JP	2000	-2910	089	Α		2000	0925										
	JP	2000	-3187	752	Α		2000	1019										

AB A novel polysiloxane having the structural units of the following formula I, II and III (A1, A2 = acid-dissociable monovalent org. group, R1 = H, monovalent (halogenated) hydrocarbon, halogen, amino, R2 = monovalent (halogenated) hydrocarbon group, halogen) is disclosed. A method of prepg. such a polysiloxane, a silicon-contg. alicyclic compd. providing this polysiloxane, and a radiation-sensitive resin compn. comprising this polysiloxane are also provided. The polysiloxane is useful as a resin component for a resist material, effectively senses radiation with a short wavelength (157-248 nm), exhibits high transparency to radiation and superior dry etching properties, and excels in basic resist properties required for resist materials such as high sensitivity, resoln., developability, etc.

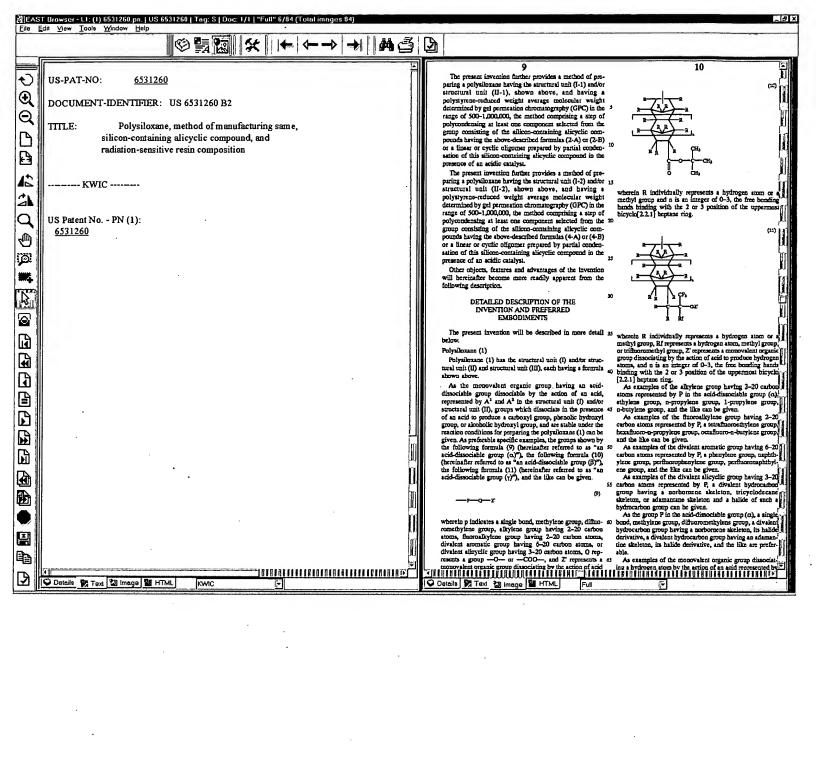
IT 365533-00-2

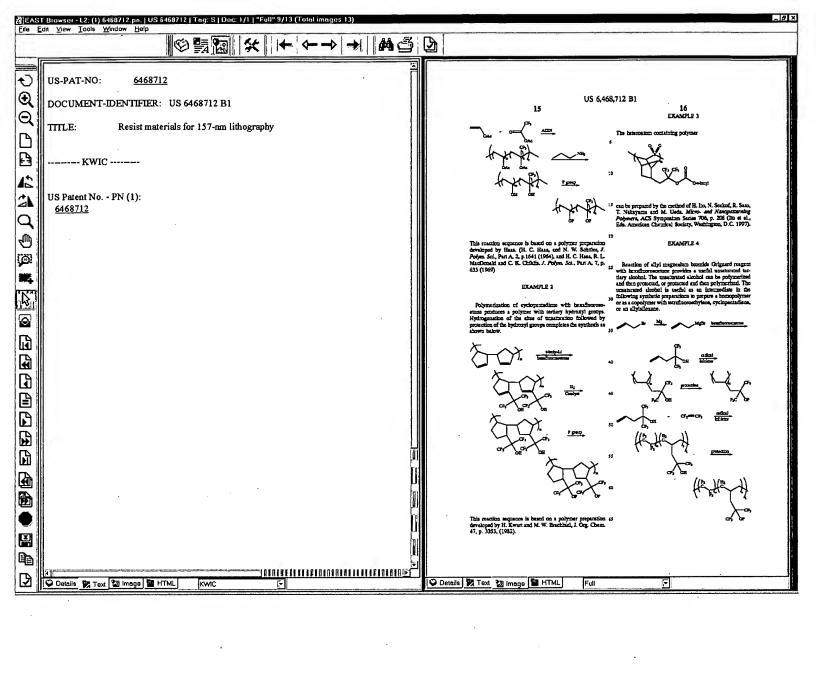
RL: RCT (Reactant); RACT (Reactant or reagent)
 (in prepn. of silicon-contg. alicyclic compd.)

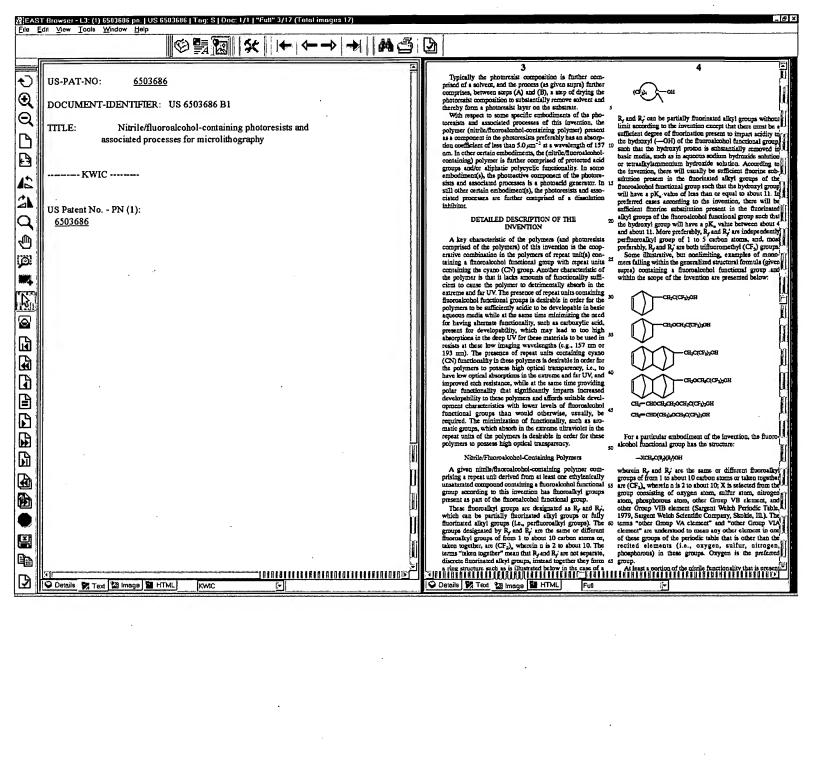
RN 365533-00-2 CAPLUS

CN 1,4:5,8-Dimethanonaphthalene-2-ethanol, 1,2,3,4,4a,5,8,8a-octahydro-alpha.,alpha.-bis(trifluoromethyl)- (9CI) (CA INDEX NAME)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT







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ANSWER 78 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN
L27
     2001:636379 CAPLUS
ΑN
DN
     135:218727
     Resist materials for 157-nm lithography
ΤI
IN
     Fedynyshyn, Theodore H.
     Massachusetts Institute of Technology, Inc., USA
PA
SO
     PCT Int. Appl., 43 pp.
     CODEN: PIXXD2
DT
     Patent
     English
LA
FAN.CNT 1
                      KIND DATE
                                           APPLICATION NO.
                                                            DATE
                      _ _ _ _
                           -----
                                           -----
                      A2
                                           WO 2001-US5907
                                                            20010226
PΙ
     WO 2001063362
                            20010830
                            20020307
     WO 2001063362
                      A3
         W: CA, JP
         RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL,
             PT, SE, TR
     US 6468712
                      B1
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                                           US 2000-513792
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                      A2
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             IE, FI, CY, TR
PRAI US 2000-513792
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                      W
     WO 2001-US5907
                            20010226
     The invention relates to photoresist materials useful in
AB
     microlithog, and to improved materials and methods for pattern formation
     on semiconductor wafers. A radiation sensitive resin compn.
     including a photo-acid generator and an aliph. polymer having
     .gtoreq.1 electron withdrawing groups adjacent to or attached to a C atom
    bearing a protected hydroxyl group, wherein the protecting group is labile
     in the presence of in situ generated acid is described. The radiation
     sensitive resin compn. can be used as a resist suitable for
     image transfer by plasma etching and enable 1 to obtain an etching image
    having high precision with high reproducibility with a high degree of
     resoln. and selectivity.
IT
     357397-06-9D, functional-group protected 357397-07-0D,
     functional-group protected 357397-08-1D, functional-group
    protected 357397-09-2D, functional-group protected
     RL: DEV (Device component use); POF (Polymer in formulation); TEM
     (Technical or engineered material use); USES (Uses)
        (pos. photoresist compn. for 157-nm lithog. using)
RN
     357397-06-9 CAPLUS
CN
    Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-,
    polymer with tetrafluoroethene (9CI) (CA INDEX NAME)
     CM
          1
         196314-61-1
     CMF C11 H12 F6 O
           OH
           - C— CF3
           CF<sub>3</sub>
```

CRN 116-14-3

RN 357397-07-0 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1 CMF C11 H12 F6 O

RN 357397-08-1 CAPLUS

CN 2-Propenoic acid, 1,1-dimethylethyl ester, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1 CMF C11 H12 F6 O

CM 2

CRN 1663-39-4 CMF C7 H12 O2

RN 357397-09-2 CAPLUS

CN 2,5-Furandione, polymer with .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2 .2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 196314-61-1

CMF C11 H12 F6 O

CM 2

CRN 108-31-6 CMF C4 H2 O3

 \cdot L27 ANSWER 79 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN AN

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2001:380920 CAPLUS
     134:359532
DN
     Nitrile/fluoroalcohol-containing photoresists and associated processes for
TI
     microlithography
     Fryd, Michael; Schadt, Frank Leonard, III; Periyasamy, Mookkan
IN
PΑ
     E.I. Du Pont De Nemours and Company, USA
SO
     PCT Int. Appl., 40 pp.
     CODEN: PIXXD2
DT
     Patent
     English
LΑ
FAN.CNT 1
                                           APPLICATION NO. DATE
     PATENT NO.
                      KIND DATE
                            -----
                                           -----
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                                           WO 2000-US31136 20001114
     WO 2001037047
                       A2
                            20010525
PΙ
     WO 2001037047
                       Α3
                            20020328
            AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN,
             CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR,
             HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT,
             LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU,
             SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN,
             YU, ZA, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM
         RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW, AT, BE, CH, CY,
             DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR, BF,
             BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG
     EP 1240554
                       A2
                           20020918
                                           EP 2000-978579
                                                           20001114
             AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,
             IE, SI, LT, LV, FI, RO, MK, CY, AL, TR
                            20030107
                                           US 2000-714782
                                                            20001116
                       В1
PRAI US 1999-166035P
                            19991117
                       Ρ
     WO 2000-US31136
                       W
                            20001114
     The invention pertains to photoimaging and use of photoresists (pos.- and
AB
     neg.-working) for imaging in the prodn. of semiconductor devices and to
     photoresists contg. polymer compns. having high UV transparency,
     particularly at short wavelengths, e. g., 157 nm or 193 nm, that are
     useful as base resins in resists and potentially, in many other
     applications. Nitrile/fluoroalc.-contg. photoresists and assocd.
     processes for microlithog. are described. These photoresists are
     comprised of a fluoroalc. functional group and a nitrile-contg. compd.
     which together simultaneously impart high UV transparency and development
     in basic media to these materials. The materials have high UV
     transparency, particularly at short wavelengths, e.g., 157 nm, which makes
     them highly useful for lithog. at these short wavelengths.
ΙT
     339265-99-5P 339266-00-1P 339266-01-2P
     RL: NUU (Other use, unclassified); PNU (Preparation, unclassified); POF
     (Polymer in formulation); PREP (Preparation); USES (Uses)
        (prepn. of polymers for nitrile/fluoroalc.-contg. compns. for
        photoresists having high UV transparency)
RN
     339265-99-5 CAPLUS
     2-Propenoic acid, 2-methyl-, polymer with 2-propenenitrile and
CN
     5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]bicyclo[2
     .2.1]hept-2-ene (9CI) (CA INDEX NAME)
     CM
          1
     CRN
          305815-64-9
     CMF
         C13 H16 F6 O3
```

CRN 107-13-1 CMF C3 H3 N

 $H_2C = CH - C = N$

CM 3

CRN 79-41-4 CMF C4 H6 O2

$$^{
m CH_2}_{||}_{
m Me}-^{
m C-CO_2H}$$

RN 339266-00-1 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1,1-dimethylethyl ester, polymer with 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-2-propanol and 2-propenenitrile (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 2

CRN 585-07-9 CMF C8 H14 O2

$H_2C = CH - C = N$

RN 339266-01-2 CAPLUS

CN 2-Propenoic acid, 2-methyl-, polymer with 1,1-dimethylethyl 2-methyl-2-propenoate, 2-propenenitrile and 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-64-9 CMF C13 H16 F6 O3

CM 2

CRN 585-07-9 CMF C8 H14 O2

$$\begin{array}{c|c} & \text{O} & \text{CH}_2 \\ \parallel & \parallel \\ \text{t-BuO-C-C-Me} \end{array}$$

CM 3

CRN 107-13-1 CMF C3 H3 N

$$H_2C = CH - C = N$$

CM 4

CRN 79-41-4 CMF C4 H6 O2

$$^{{
m CH}_2}_{||}$$
 Me- C- $^{{
m CO}_2}{
m H}$

IT 305815-63-8P 305815-64-9P

RL: NUU (Other use, unclassified); RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent); USES (Uses)

(prepn. of, for nitrile/fluoroalc.-contg. polymer compns. for photoresists having high UV transparency)

RN

CN

305815-63-8 CAPLUS 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3hexafluoro- (9CI) (CA INDEX NAME)

L27 ANSWER 84 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:806346 CAPLUS

DN 134:200397

TI Polymers for 157-nm photoresist applications: a progress report

AU Patterson, Kyle; Yamachika, Miko; Hung, Raymond J.; Brodsky, Colin J.; Yamada, Shintaro; Somervell, Mark H.; Osborn, Brian; Hall, Daniel; Dukovic, Gordana; Byers, Jeffrey; Conley, Willard; Willson, C. Grant

CS Dep. Chemistry and Chem. Eng., The Univ. Texas at Austin, Austin, TX, USA

Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 365-374

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DT Journal

LA English

AB Finding materials that offer the all of the characteristics required of photoresist matrix resin polymers while trying to maintain a high level of transparency at 157 nm is a daunting challenge. To simplify this task, the authors have broken the design of these polymers down into subunits, each of which was responsible for a required function in the final material. In addn., the authors have begun collecting gas-phase VUV spectra of these potential subunits to measure their individual absorbance contributions. Progress on developing materials for each of these subunits were presented along with plans for future studies.

IT 328114-62-1

RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)

(model polymer; design of polymers and their subunits for 157-nm photoresist applications)

RN 328114-62-1 CAPLUS

CN 2,5-Furandione, polymer with 5-[2-(ethoxymethoxy)-3,3,3-trifluoro-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-ene (9CI) (CA INDEX NAME)

CM 1

CRN 328114-61-0 CMF C14 H18 F6 O2

CM 2

CRN 108-31-6 CMF C4 H2 O3

RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L27 ANSWER 85 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:806336 CAPLUS

DN 134:214824

TI Using alicyclic polymers in top surface imaging systems to reduce line-edge roughness

AU Somervell, Mark H.; Fryer, David S.; Osborn, Brian; Patterson, Kyle; Cho, Sungseo; Byers, Jeffrey D.; Willson, C. Grant

CS Univ. of Texas at Austin, Dallas, TX, USA

SO Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 270-282

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DT Journal

LA English

Top surface imaging (TSI) systems based on vapor phase silylation have AB been investigated for use at a variety of wavelengths. This approach to generating high aspect ratio, high resoln. images held great promise particularly for 193 nm and extreme-UV lithog. applications. Several 193 nm TSI systems have been described that produce very high resoln. (low k factor) images with wide process latitude. However, because of the line edge roughness assocd. with the final images, TSI systems have fallen from favor. In fact, top surface imaging and line edge roughness have become synonymous in the minds of most. Most of the 193 nm TSI systems are based on poly(p-hydroxystyrene) resins. These polymers have an unfortunate combination of properties that limit their utility in this application. These limiting properties include (1) high optical d., (2) poor silylation contrast, and (3) low glass transition temp. of the silylated material. These shortcomings are related to inherent polymer characteristics and are responsible for the pronounced line edge roughness in the poly(p-hydroxystyrene) systems. The authors synthesized certain alicyclic polymers that have higher transparency and higher glass transition temps. Using these polymers, the authors demonstrated the ability to print high resoln. features with very smooth sidewalls. paper describe the synthesis and characterization of the polymers and their application to top surface imaging at 193 nm. The anal. that was used to tailor the processing and the polymer's phys. properties to achieve optimum imaging is also described.

IT 214079-69-3

RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)

(lithog. performance of alicyclic-polymer based chem. amplified photoresists in top surface imaging for redn. of line-edge roughness)

RN 214079-69-3 CAPLUS

Carbonic acid, 1-(bicyclo[2.2.1]hept-5-en-2-ylmethyl)-2,2,2-trifluoro-1-(trifluoromethyl)ethyl 1,1-dimethylethyl ester, polymer with sulfur dioxide, alternating (9CI) (CA INDEX NAME)

CM 1

CN

CRN 196314-63-3 CMF C16 H20 F6 O3

CRN 7446-09-5 CMF O2 S

0 = s = 0

RE.CNT 17 THERE ARE 17 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L27 ANSWER 86 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:806316 CAPLUS

DN 134:200382

TI Negative-tone 193-nm resists

AU Cho, Sungseo; Vander Heyden, Anthony; Byers, Jeffrey D.; Willson, C. Grant

CS Univ. of Texas at Austin, Austin, TX, USA

SO Proceedings of SPIE-The International Society for Optical Engineering (2000), 3999(Pt. 1, Advances in Resist Technology and Processing XVII), 62-73

CODEN: PSISDG; ISSN: 0277-786X

PB SPIE-The International Society for Optical Engineering

DT Journal

LA English

A great deal of progress has been made in the design of single layer pos. AΒ tone resists for 193 nm lithog. Com. samples of such materials are now available from many vendors. The patterning of certain levels of devices profits from the use of neg. tone resists. There have been several reports of work directed toward the design of neg. tones resists for 193 nm exposure but, none have performed as well as the pos. tone systems. Polymers with alicyclic structures in the backbone have emerged as excellent platforms from which to design pos. tone resists for 193 nm exposure. The authors report the adaptation of this class of polymers to the design of high performance neg. tone 193 nm resists. New systems have been prepd. that are based on a polarity switch mechanism for modulation of the dissoln. rate. The systems are based on a polar, alicyclic polymer backbone that includes a monomer bearing a glycol pendant group that undergoes the acid catalyzed pinacol rearrangement upon exposure and bake to produce the corresponding less polar ketone. This monomer was copolymd. with maleic anhydride and a norbornene bearing a bis-trifluoromethylcarbinol. The rearrangement of the copolymer was monitored by FT-IR as a function of temp. The synthesis of the norbornene monomers will be presented together with characterization of copolymers of these monomers with maleic anhydride. The lithog. performance of the new resist system will also be presented.

IT 327610-81-1P

RL: PRP (Properties); SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(photoresist for 193 nm lithog. contg. terpolymer of maleic anhydride and norbornene with bis-trifluoromethylcarbinol and norbornene with glycol pendant group that undergoes acid catalyzed pinacol rearrangement)

RN 327610-81-1 CAPLUS

CN 2,5-Furandione, polymer with 1-bicyclo[2.2.1]hept-5-en-2-yl-2,3-dimethyl-2,3-butanediol and .alpha.,.alpha.-bis(trifluoromethyl)bicyclo[2.2.1]hept-5-ene-2-ethanol (9CI) (CA INDEX NAME)

CM 1

CRN 327610-80-0 CMF C13 H22 O2

CRN 196314-61-1 CMF C11 H12 F6 O

CM 3.

CRN 108-31-6 CMF C4 H2 O3

IT 196314-61-1P

RL: RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent)

(polymn. with maleic anhydride and (dihydroxydimethylbutyl)bicyclo[2.2.

1]heptene in synthesis of polymer photoresists for 193 nm

lithog.)

RN 196314-61-1 CAPLUS

CN Bicyclo[2.2.1]hept-5-ene-2-ethanol, .alpha.,.alpha.-bis(trifluoromethyl)-(9CI) (CA INDEX NAME)

RE.CNT 29 THERE ARE 29 CITED REFERENCES AVAILABLE FOR THIS RECORD ALL CITATIONS AVAILABLE IN THE RE FORMAT

L27 ANSWER 87 OF 89 CAPLUS COPYRIGHT 2003 ACS on STN

AN 2000:790750 CAPLUS

DN 133:357252

TI Fluorinated polymers, photoresists and processes for microlithography

IN Feiring, Andrew Edward; Feldman, Jerald

PA E.I. Du Pont De Nemours and Company, USA

SO PCT Int. Appl., 69 pp. CODEN: PIXXD2 DT Patent English LA FAN.CNT 1 PATENT NO. KIND DATE APPLICATION NO. DATE _ _ _ _ ----------20001109 WO 2000067072 **A**1 WO 2000-US11539 20000428 PΤ AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM RW: GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW, AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG 20020306 EP 2000-928563 20000428 EP 1183571 A1 AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO JP 2000-615852 20000428 JP 2002543469 T2 20021217 PRAI US 1999-132373P Ρ 19990504 WO 2000-US11539 W 20000428 AΒ Fluorinated polymers, photoresists and assocd. processes for microlithog. are described. These polymers and photoresists are comprised of a fluoroalc. functional group which simultaneously imparts high UV transparency and developability in basic media to these materials. materials of this invention have high UV transparency, particularly at short wavelengths, e.g. 157 nm, which makes them highly useful for lithog. at these short wavelengths. IT 305815-63-8P 305815-64-9P RL: RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent) (fluorinated polymers, photoresists and processes for microlithog.)

2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-

305815-63-8 CAPLUS

hexafluoro- (9CI) (CA INDEX NAME)

RN

CN

RN 305815-64-9 CAPLUS
CN Bicyclo[2.2.1]hept-2-ene, 5-[3,3,3-trifluoro-2-(methoxymethoxy)-2-(trifluoromethyl)propoxy]- (9CI) (CA INDEX NAME)

CN 2-Propanol, 2-[(bicyclo[2.2.1]hept-5-en-2-yloxy)methyl]-1,1,1,3,3,3-hexafluoro-, polymer with bicyclo[2.2.1]hept-2-ene and tetrafluoroethene (9CI) (CA INDEX NAME)

CM 1

CRN 305815-63-8 CMF C11 H12 F6 O2

CM 2

CRN 498-66-8 CMF C7 H10

